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Part Number: [5013311307](#)
Status: **Active**
Overview: [picoclasp](#)
Description: 1.00mm (.039") Pitch Pico-Clasp™ Wire-to-Board Header, Surface Mount, Single Row, Vertical, with Positive Lock, 13 Circuits, with Cover Tape, Lead-free

Documents:

[3D Model](#) [Product Specification PS-501331-001 \(PDF\)](#)
[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)

General

Product Family	PCB Headers
Series	501331
Application	Wire-to-Board
Overview	picoclasp
Product Name	Pico-Clasp™

Physical

Breakaway	No
Circuits (Loaded)	13
Color - Resin	Natural
Durability (mating cycles max)	30
Glow-Wire Compliant	No
Lock to Mating Part	Yes
Material - Metal	Phosphor Bronze
Material - Plating Mating	Tin
Material - Plating Termination	Tin
Material - Resin	Nylon
Number of Rows	1
Orientation	Vertical
PCB Locator	No
PCB Retention	Yes
Packaging Type	Embossed Tape on Reel
Pitch - Mating Interface (in)	0.039 In
Pitch - Mating Interface (mm)	1.00 mm
Polarized to Mating Part	Yes
Polarized to PCB	No
Robotic Placement	Vacuum Pick-Up Tape
Stackable	No
Temperature Range - Operating	-40°C to +85°C
Termination Interface: Style	Surface Mount

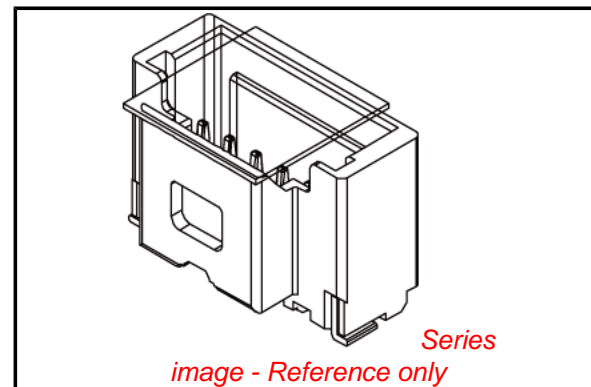
Electrical

Current - Maximum per Contact	1A
Voltage - Maximum	50V AC (RMS)/DC

Material Info

Reference - Drawing Numbers

Packaging Specification	SPK-501331-001
Product Specification	PS-501331-001, RPS-501331-001, RPS-501331-002, RPS-501331-003, RPS-501331-005, RPS-501331-006, RPS-501331-007, RPS-501940-001, RPS-501940-002
Sales Drawing	SD-501331-002, SD-501331-004



EU RoHS

ELV and RoHS Compliant
REACH SVHC
 Not Reviewed
Halogen-Free
Status
Not Reviewed

China RoHS



Need more information on product environmental compliance?

Email productcompliance@molex.com
 For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series

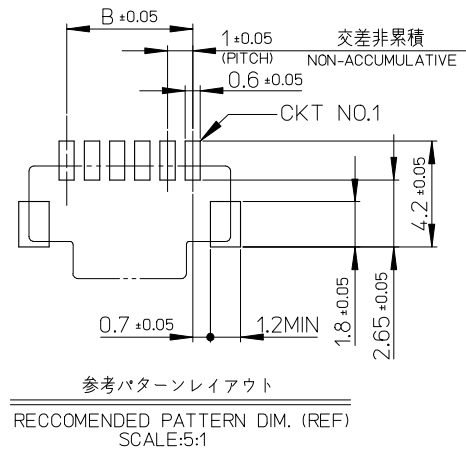
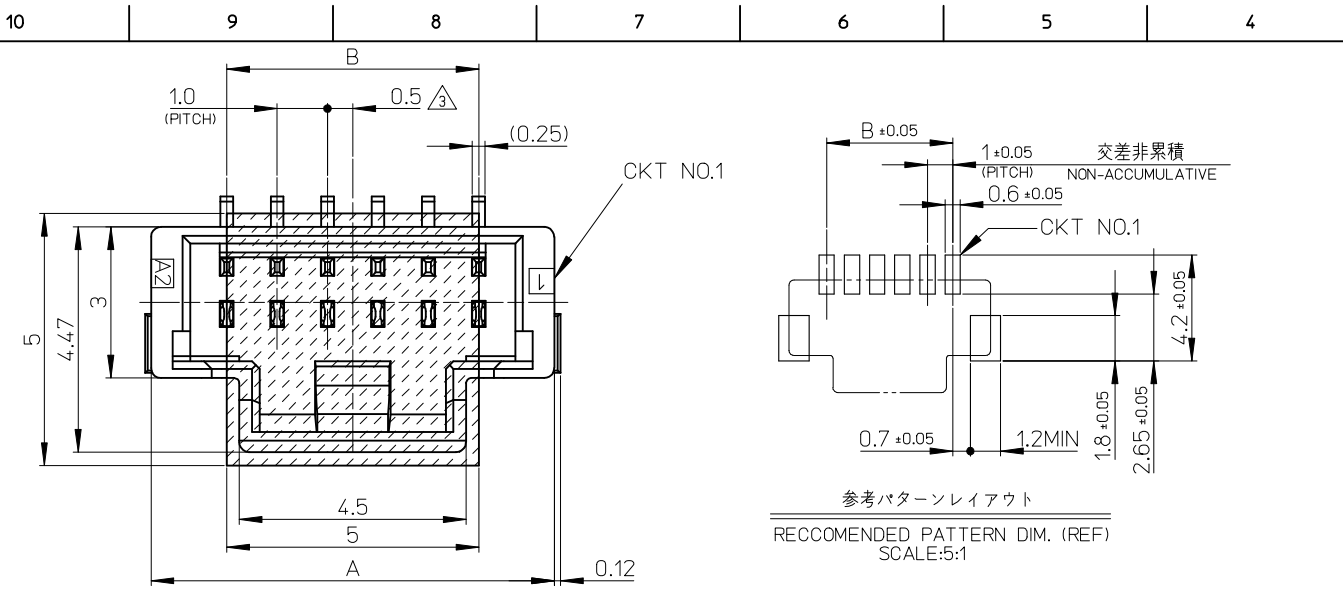
[501331Series](#)

Mates With

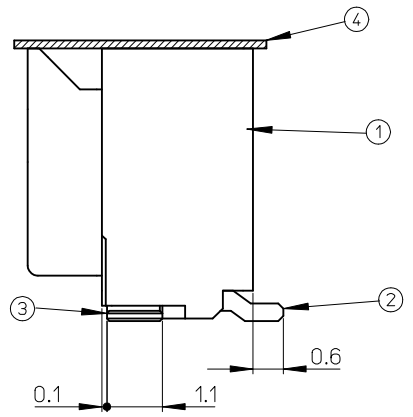
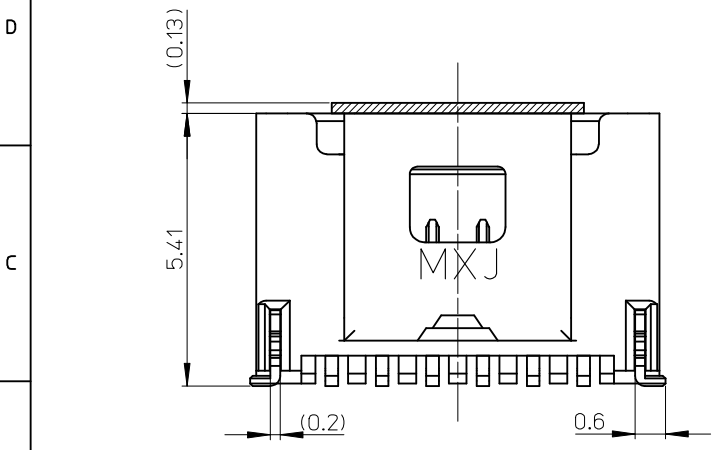
[501330](#) Pico-Clasp™ Wire-to-Board Female Housing

This document was generated on 05/26/2010

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番号 NO.	部品 PART	材質 MATERIAL
①	ウエハー WAFER	耐熱ナイロン樹脂 UL94V-0 色:表参照 HEAT RESISTANCE NYLON UL94V-0, COLOR:SEE TABLE
②	ソルダーピン SOLDER PIN	りん青銅 PHOSPHOR BRONZE 錫メッキ: 1.0 μm MIN. TIN ニッケルメッキ(下地): 1.0 μm MIN. NICKEL(UNDER PLATING)
③	ネイル NAIL	りん青銅 PHOSPHOR BRONZE 錫メッキ: 1.0 μm MIN. TIN ニッケルメッキ(下地): 1.0 μm MIN. NICKEL(UNDER PLATING)
④	カバーテープ COVER TAPE	ポリイミドテープ POLYIMIDE TAPE



14.0	17.0	15
13.0	16.0	14
12.0	15.0	13
11.0	14.0	12
10.0	13.0	11
9.0	12.0	10
8.0	11.0	9
7.0	10.0	8
6.0	9.0	7
5.0	8.0	6
B	A	極数 CIRCUITS

※対応可能な極数は、別途お問い合わせ下さい。

- NOTES.
1. 嵌合相手: 501330-****
MATE WITH: 501330-****
 2. ソルダーピン及びネイル平坦度は、0.1MAX.
SOLDER PIN AND NAIL COPLANARITY TO BE 0.1MAX.
 3. 極数=偶数に適用
APPLY FOR CKT SIZE=EVEN
 4. 2~5極は、SD-501331-001を参照下さい。
REFER TO SD-501331-001 ABOUT 2-5CKT.
 5. ELV及びRoHS適合品。
ELV AND RoHS COMPLIANT.

REVISED		GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE		DESIGN UNITS		THIRD ANGLE PROJECTION	
EC NO: J2010-0339	DRWN:IMAKAWA01 2009/09/01	10 UNDER	±0.2	MM ONLY		10:1		METRIC		THIRD ANGLE PROJECTION	
CHKD:HATSUMOTO 2009/09/01	APPR:HIRATA 2009/09/01	10 OVER 30 UNDER	±0.25	DRAWN BY	DATE	TITLE		1.0 WIRE TO BOARD CONN. WAFER ASS'Y (1-ROW S/T) 6-15CKT			
REV	DESCRIPTION	30 OVER	±0.3	NYOSHIDA	2004/07/30	MOLEX INCORPORATED					
		ANGULAR ±3 °		CHECKED BY	DATE	DOCUMENT NO.		SHEET NO.			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MYAGI	2004/07/30	SD-501331-002		1 OF 2			
				APPROVED BY	DATE	SEE TABLE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
				MIYAZAWA	2004/07/30						
				MATERIAL NO.							
				SIZE	A3						

F

紫 PA46 VIOLET	橙 PA46 ORANGE	茶 PA46 BROWN	緑 PA46 GREEN	色 COLOR
501331-1597	501331-1587	501331-1577	501331-1567	15
501331-1497	501331-1487	501331-1477	501331-1467	14
501331-1397	501331-1387	501331-1377	501331-1367	13
501331-1297	501331-1287	501331-1277	501331-1267	12
501331-1197	501331-1187	501331-1177	501331-1167	11
501331-1097	501331-1087	501331-1077	501331-1067	10
501331-0997	501331-0987	501331-0977	501331-0967	9
501331-0897	501331-0887	501331-0877	501331-0867	8
501331-0797	501331-0787	501331-0777	501331-0767	7
501331-0697	501331-0687	501331-0677	501331-0667	6
EMBOSSSED PACKAGE	EMBOSSSED PACKAGE	EMBOSSSED PACKAGE	EMBOSSSED PACKAGE	極数
オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	CIRCUITS

E

D

CONNECTOR SERIES No. 501331-***9


青 PA46 BLUE	黄 PA46 YELLOW	赤 PA46 RED	黒 PA46 BLACK	自然色 PA6T NATURAL	色 COLOR
501331-1547	501331-1537	501331-1527		501331-1507	15
501331-1447	501331-1437	501331-1427		501331-1407	14
501331-1347	501331-1337	501331-1327		501331-1307	13
501331-1247	501331-1237	501331-1227		501331-1207	12
501331-1147	501331-1137	501331-1127		501331-1107	11
501331-1047	501331-1037	501331-1027		501331-1007	10
501331-0947	501331-0937	501331-0927	501331-0917	501331-0907	9
501331-0847	501331-0837	501331-0827	501331-0817	501331-0807	8
501331-0747	501331-0737	501331-0727		501331-0707	7
501331-0647	501331-0637	501331-0627	501331-0617	501331-0607	6
EMBOSSSED PACKAGE	EMBOSSSED PACKAGE	EMBOSSSED PACKAGE	EMBOSSSED PACKAGE	EMBOSSSED PACKAGE	極数
オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	CIRCUITS

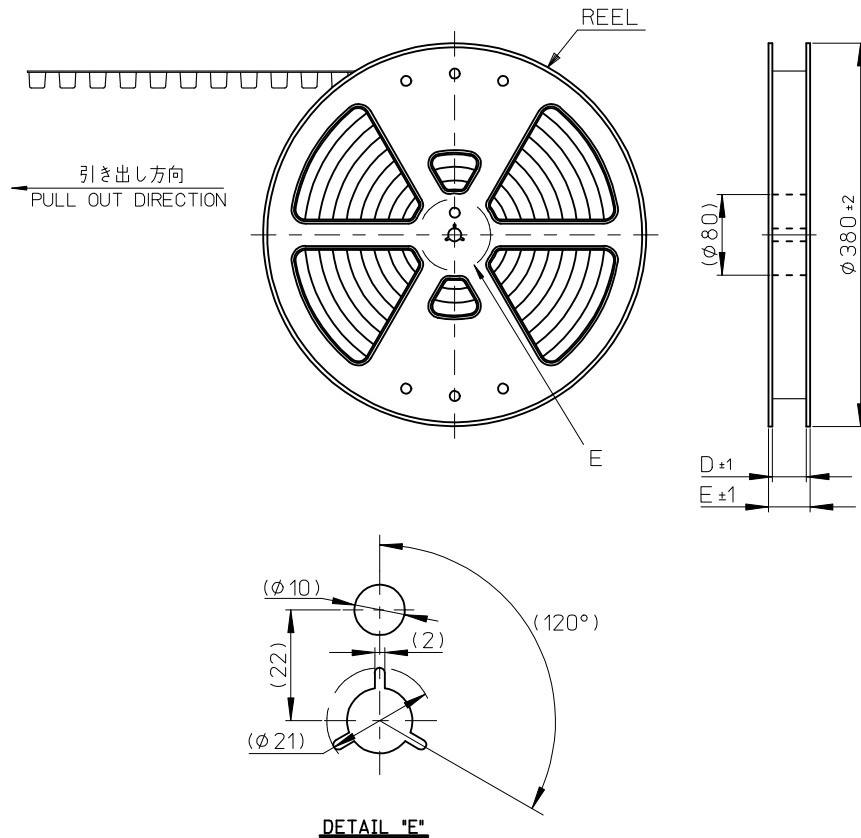
CONNECTOR SERIES No. 501331-***9

C

B

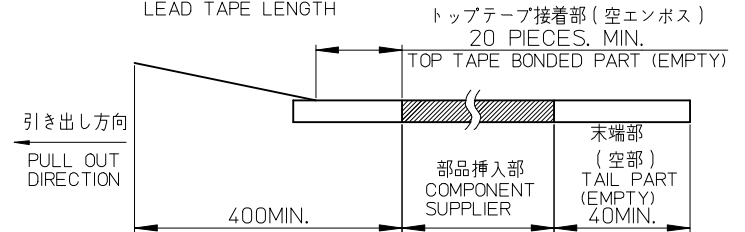
A

REVISED EC NO: J2010-0339 DRWN: TNAGAWA01 2009/09/01 CHKD: HMATSUMOTO 2009/09/01 APPR: HIRATA 2009/09/01	DESCRIPTION H	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	±0.2	DRAWN BY NYOSHIDA	DATE 2004/07/30	TITLE 1.0 WIRE TO BOARD CONN. WAFER ASS'Y (1-ROW S/T) 6-15CKT			
		10 OVER 30 UNDER	±0.25	CHECKED BY MYAGI	DATE 2004/07/30	 MOLEX INCORPORATED DOCUMENT NO. SD-501331-002 SHEET NO. 2 OF 2			
		30 OVER	±0.3	APPROVED BY MIYAZAWA	DATE 2004/07/30				
ANGULAR ±3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE TABLE					
				SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



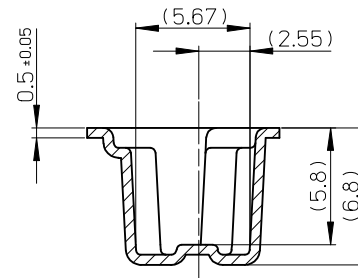
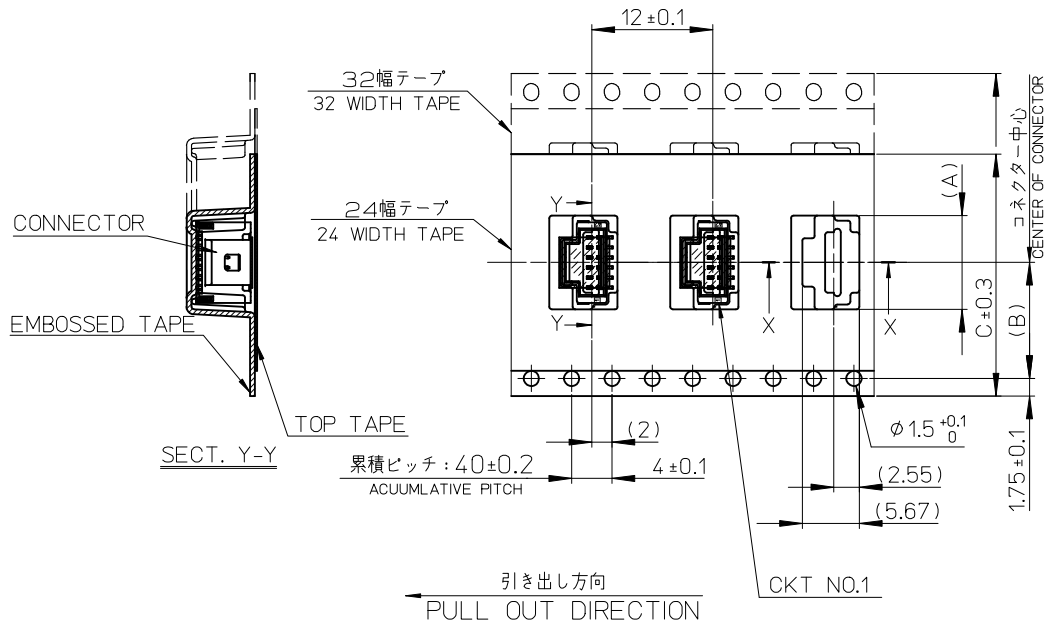
NOTES.

- 製品詳細寸法については製品単体図面を参照ください。
ABOUT DETAILED DIMENSION, SEE PRODUCT DRAWING.
- 梱包数量：1100個/リール
NUMBER OF CONNECTORS：1100PIECES/REEL
- リードテープ長さ
LEAD TAPE LENGTH



- 材料
MATERIAL
キャリアテープ：ポリプロピレン
CARRIER TAPE：POLYPROPYLENE
トップテープ：PET、PE、REF
TOP TAPE
リール：ポリスチレン (リサイクル材を含む)
REEL：POLYSTYLENE (RECYCLE MATERIAL CONTAINED)
- ELV 及び RoHS適合品
ELV AND RoHS COMPLIANT.
- ハイバリア梱包 (シリカゲル入り) 対応品である。(501331-**07除く)
THIS PRODUCT IS HIGH BARRIER PACKAGE.(WITH SILICAGEL)
(BESIDES 501331-**07)
- 開梱後の保管条件に注意のこと。(ハイバリア品対象：PS-501331-001参照)
REFER TO PS-501331-001(HIGH BARRIER PRODUCT)
FOR CONDITIONS AFTER OPEN.

REVISED EC NO: J2010-0339 DRWN: TAKAGAWA01 2009/09/01 CHKD: MATSUMOTO 2009/09/01 APPR: HIRATA 2009/09/01	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	±0.2	DRAWN BY NYOSHIDA	DATE 2005/01/18	TITLE 1.0 WIRE TO BOARD CONN. WAFER ASS'Y (1-ROW S/T) EMBSTP PKG				
		10 OVER 30 UNDER	±0.25	CHECKED BY MYAGI	DATE 2005/01/18	MOLEX INCORPORATED				
		30 OVER	±0.3	APPROVED BY ANODA	DATE 2005/01/18	DOCUMENT NO. SD-501331-004				
ANGULAR ±1 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE SHEET 3		SHEET NO. 1 OF 3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		



SECT. X-X
(SCALE 4:1)

37.4	33.4	32	14.2	18.3	15
				17.3	14
				16.3	13
29.4	25.4	24	11.5	15.3	12
				14.3	11
				13.3	10
				12.3	9
				11.3	8
				10.3	7
E	D	C	(B)	9.3	6
				(A)	極数 CIRCUITS

CONNECTOR SERIES No. 501331-***9

REVISED EC NO: J2010-0339 DRWN: TAKAGAWA01 2009/09/01 CHKD: MATSUMOTO 2009/09/01 APPR: HIRATA 2009/09/01	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
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	ANGULAR ± 1 °		MATERIAL NO.	DOCUMENT NO.				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE SHEET 3		SD-501331-004		SHEET NO. 2 OF 3		

F

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EMBOSSSED PACKAGE オーダー番号 ORDER NO.	EMBOSSSED PACKAGE オーダー番号 ORDER NO.	EMBOSSSED PACKAGE オーダー番号 ORDER NO.	EMBOSSSED PACKAGE オーダー番号 ORDER NO.	極数 CIRCUITS

E

D

青 BLUE	黄 YELLOW	赤 RED	黒 BLACK	自然色 NATURAL	色 COLOR
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501331-1047	501331-1037	501331-1027		501331-1007	10
501331-0947	501331-0937	501331-0927	501331-0917	501331-0907	9
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501331-0647	501331-0637	501331-0627	501331-0617	501331-0607	6
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C

B

A

REVISED EC NO: J2010-0339 DRWN: TNAGAWA01 2009/09/01 CHKD: HMATSUMOTO 2009/09/01 APPR: HIRATA 2009/09/01	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
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		10 OVER 30 UNDER	±0.25	CHECKED BY MYAGI	DATE 2005/01/18	MOLEX INCORPORATED				
		30 OVER	±0.3	APPROVED BY ANODA	DATE 2005/01/18	DOCUMENT NO. SD-501331-004				
		ANGULAR ±1 °		MATERIAL NO. SEE TABLE		SHEET NO. 3 OF 3				
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				